

ABSTRACT OF THE DISCLOSURE

In a method of fabricating a resin-sealed semiconductor device, a semiconductor device is disposed inside a cavity of a mold and resin is injected through a gate of the mold into
5 the cavity to seal the semiconductor device with the resin in a state where portions of lead portions are exposed. The gate is disposed only in a surface of the cavity facing the surface of the semiconductor chip. The resin is injected through the gate towards the surface of the semiconductor chip.